



RECOMMENDED PCB LAYOUT

NOTES:

- INSULATOR:LCP . COLOR-BLACK
- USB CONTACT: PHOSPHOR BRONZE,0.15mm THICKNESS, GOLD PLATED ON CONTACT AREA, GOLD FLASH OR 50 U" TIN PLATED ON SOLDER TAIL, 80 U" MIN. NICKEL UNDER PLATED OVERALL.
- SHELL: STAINLESS STEEL ,0.3 THICKNESS,GOLD FLASH OR 40U" NICKEL PLATED ON THE SOLDERING TAB.

Pin Assignments

Shell	Shield
10	MicB_SSRX+
9	MicB_SSRX-
8	GND_DRAIN
7	MicB_SSTX+
6	MicB_SSTX-
5	GND
4	ID

ITEM	DESCRIPTION	PIN NO.	SIGNAL NAME
3	CONTACT	3	D+
2	SHELL	2	D-
1	HOUSING	1	VBUS

TOLERANCE:		UNIT	深圳市创勤科技有限公司 Shenzhen Chuangqin Technology Co., Ltd.			
X. ± 0.50	X.° ± 1°	MM				
.X ± 0.30	.X° ± 1°	SHEET	DRAW:		LIN YUN	2009.07.22
.XX ± 0.20	.XX° ± 1.0°	1/1	DESIGN:			P2N: CQ042-MF3S0511702
.XXX ± 0.10		SCALE	CHECK:			ITEM: Micro USB 3.0 B/F SMT ( DIP SHELL)
		1:1	APPR:			DRW NO:
		REV: B				